

Notice of Allowability	Application No.	Applicant(s)
	10/661,180	QIN ET AL.
	Examiner	Art Unit
	Boris Benenson	2836
The MAILING DATE of this communication appears on the cover sheet with the correspondence address All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS. This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.		
1. This communication is responsive to <u>09/12/2003</u> .		
2. X The allowed claim(s) is/are 1-27.		
 3. Acknowledgment is made of a claim for foreign priority unall a) All b) Some* c) None of the: Certified copies of the priority documents have Certified copies of the priority documents have Copies of the certified copies of the priority documents have International Bureau (PCT Rule 17.2(a)). * Certified copies not received: 	been received. been received in Application No cuments have been received in this	national stage application from the
Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application. THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.		
4. A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.		
 5. CORRECTED DRAWINGS (as "replacement sheets") must (a) including changes required by the Notice of Draftspers 1) hereto or 2) to Paper No./Mail Date (b) including changes required by the attached Examiner's Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR 1. each sheet. Replacement sheet(s) should be labeled as such in the paper No./Mail Date 	on's Patent Drawing Review (PTO s Amendment / Comment or in the (.84(c)) should be written on the draw he header according to 37 CFR 1.121	Office action of ings in the front (not the back) of (d).
6. DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT	SIT OF BIOLOGICAL MATERIAL FOR THE DEPOSIT OF BIOLOGIC	must be submitted. Note the CAL MATERIAL.
 Attachment(s) 1. ☑ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 9/12/3 1/25/5 10/20/05 4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material 	6. Interview Summary Paper No./Mail Da 8), 7. Examiner's Amend	ate

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Detailed Actions

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Replace sentence "This application is related to U.S. application Ser. No. _____, filed on Sep. 8, 2003 (Attorney Docket No. 03-IMP-001)" on Page 1, lines 8-9 of the Specification with -- This application is related to U.S. application Ser. No. 10/657,449, filed on Sep. 8, 2003 (Now US Patent 6,947,274)--.

Authorization for this examiner's amendment was given in a telephone interview with attorney of the case Thomas G. Eschweiler on 02/02/2006.

Allowable Subject Matter

2. Claims 1-27 are allowed.

The following is an examiner's statement of reasons for allowance:

3. Independent Claim 1 is allowable because none of the prior art of record disclose a method for clamping a wafer having a

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backside insulator wherein the determination a single phase square wave clamping voltage is based, at least in part, on a minimum residual clamping force associated with the wafer and the electrostatic chuck and a surface topography of the leaky dielectric layer in combination with the other claim limitations.

- 4. Independent Claim 17 is allowable because none of the prior art of record disclose a system for clamping a wafer having a backside insulator, wherein the J-R electrostatic chuck is operable to maintain a minimum residual clamping force during a polarity switch of the single-phase square wave clamping voltage in combination with the other claim limitations.
- 5. Claims 2-16 and 18-27 are dependent on allowable claims and therefore allowable.

Related Prior Art

6. Use of Johnsen-Rahbek effect in systems for clamping a semiconductor wafer having backside insulator is well known in the art. A known problem to be solved is a relatively long time required for dissipation electrostatic charges accumulated during processing (dechucking).

Kumar et al. (5,880,924) disclose an Electrostatic Chuck Capable Of Rapidly Dechucking A Substrate wherein "The chuck further comprises a discharge electrode electrically isolated Application/Control Number: 10/661,180

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from the charging electrode for rapidly discharging any residual electrostatic charge accumulated in the chuck during processing" (Col.3, Lines 16-19).

Leeser (6,236,555) disclosed a Method For Rapidly Dechucking
A Semiconductor Wafer From An Electrostatic Chuck Utilizing A
Hysteretic Discharge Cycle. Leeser disclosed, "This charge
migration effect is known as the Johnsen-Rahbek effect. The
Johnsen-Rahbek effect in a monopolar chuck provides a very
effective and strong electrostatic force that retains the wafer.
However, charge removal is also very difficult for such a chuck.
To rapidly dechuck the wafer from the monopolar chuck, the
invention applies a voltage between the wafer and the electrode
that performs a hysteretic discharge cycle such that residual
charge is removed, i.e., a hysteretic electric field is
established at the interface between the wafer support surface
of the chuck and the wafer" (Col.3, Lines 15-25).

All Prior Art of the record indicate difficulties in process of "dechucking" and provide rather complicated ways to dissipate electrostatic charges accumulated in the chuck during wafer processing. None of Prior Art of the record teaches a method or a system for clamping a wafer having a backside insulator, which prevents accumulation of excessive electrostatic charges instead of dissipation of the charges.

Comments to reasons for allowance

7. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Contact information

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Boris Benenson whose telephone number is (571) 272-2048. The examiner can normally be reached on M-F (8:20-6:00) First Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Brian Sircus can be reached on (571) 272-2800 ext 36. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval

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(PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Boris Benenson Examiner Art Unit 2836

В.В.

BRIAN SIRCUS
SUPERVISORY PATENT EXAMINER

TECHTICALOGY CENTER 2500